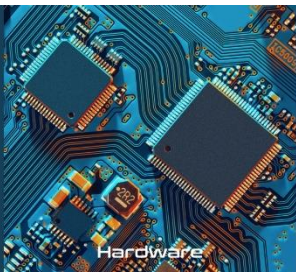


GreenPAK™

Programmable Mixed-Signal Matrix Technology

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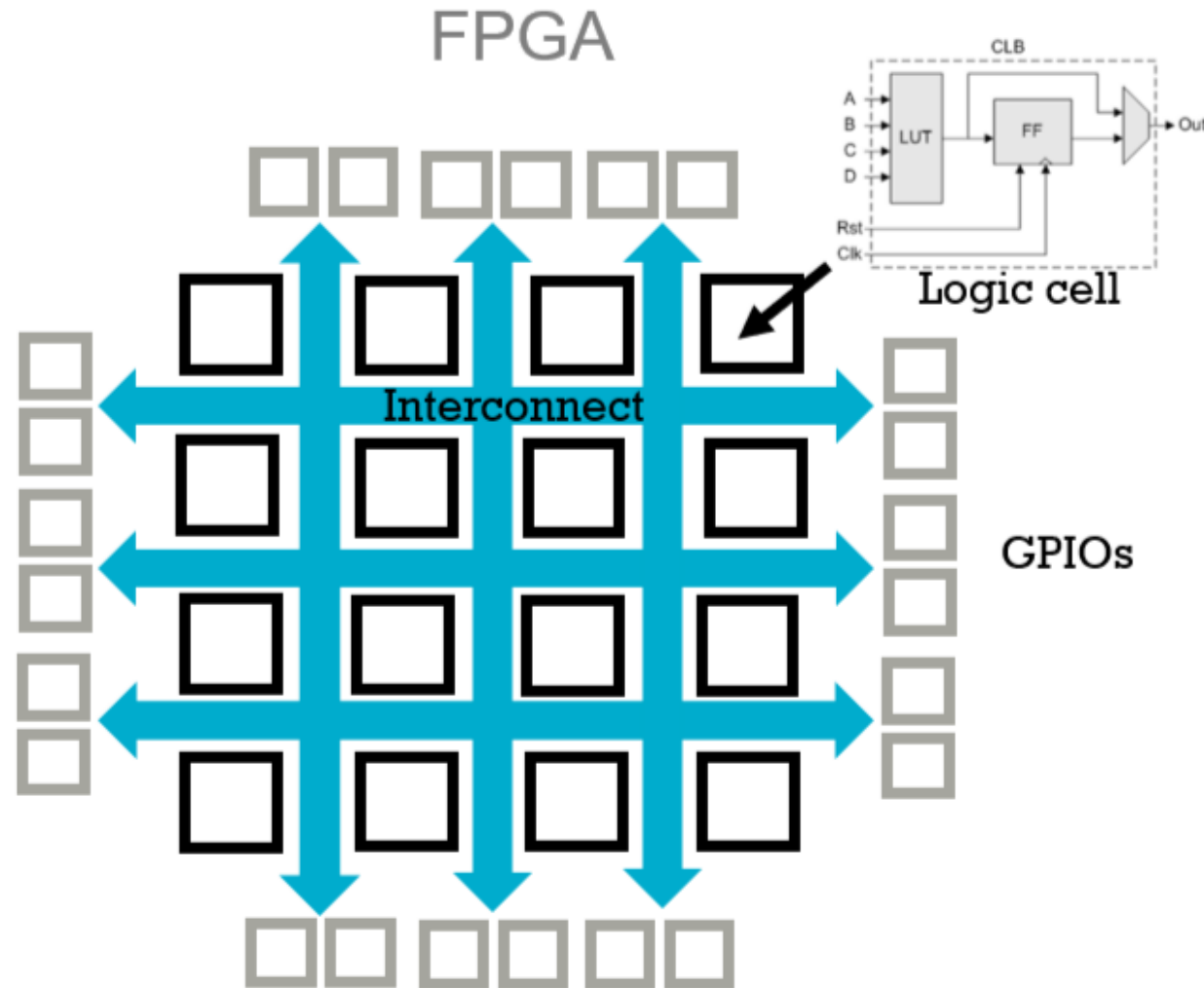
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innovatieve elektronica

Woensdag 20 maart 2024
1931 Congrescentrum 's-Hertogenbosch

What is GreenPAK: FPGA architecture

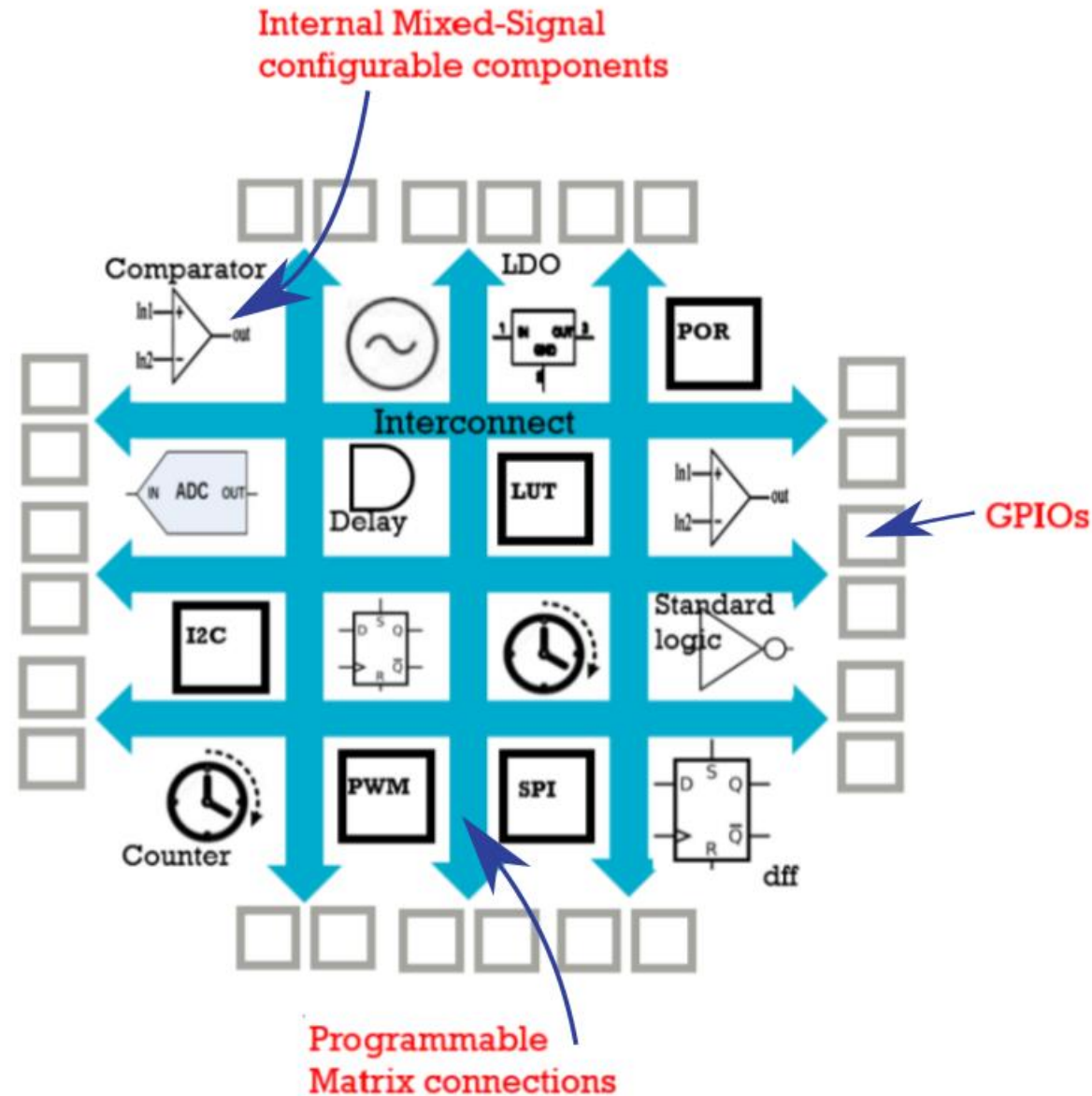


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What is GreenPAK: GreenPAK architecture



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GreenPAK Macrocells

Properties

3-bit LUT6/Pipe Delay/Ripple Counter

Type: **LUT**

IN3	IN2		
0	0	0	0
0	0	0	1
0	0	1	0
0	0	1	1
0	1	0	0
0	1	0	1
0	1	1	0
0	1	1	1
1	0	0	0
1	0	0	1
1	0	1	0
1	0	1	1
1	1	0	0
1	1	0	1
1	1	1	0
1	1	1	1

Standard gates: All to 0, All to 1, Regular shape, Invert

Apply

Internal Mixed-Signal configurable components

GPIOs

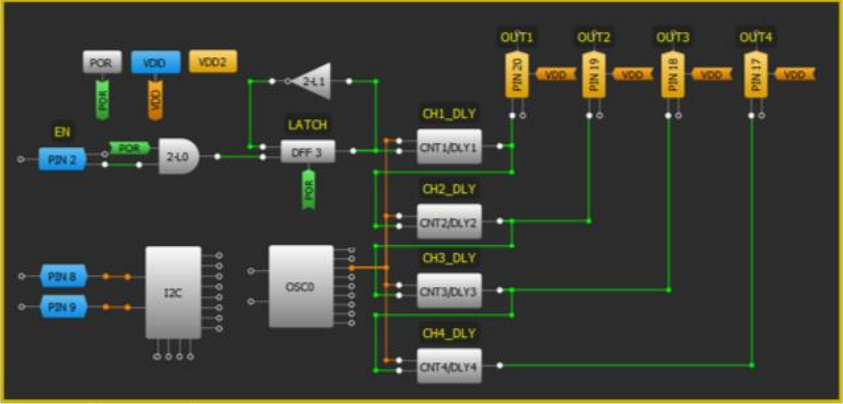
Components List

Components

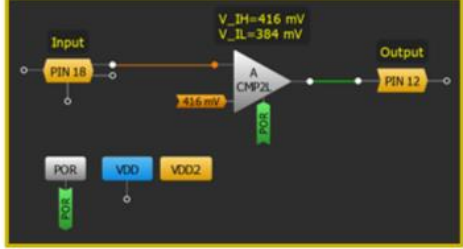
- ▼ I/O PADS
 - ✓ VDD (PIN 1)
 - ✓ PIN 2 (IO0)
 - ✓ PIN 3 (IO1)
 - ✓ PIN 4 (IO2)
 - ✓ PIN 5 (IO3)
 - ✓ PIN 6 (IO4)
 - ✓ PIN 7 (IO5)
 - ✓ PIN 8 (SCL)
 - ✓ PIN 9 (SDA)
 - ✓ PIN 10 (IO6)
 - ✓ GND (PIN 11)
 - ✓ PIN 12 (IO7)
 - ✓ PIN 13 (IO8)
 - ✓ VDD2 (PIN 14)
 - ✓ PIN 15 (IO9)
 - ✓ PIN 16 (IO10)
 - ✓ PIN 17 (IO11)
 - ✓ PIN 18 (IO12)
 - ✓ PIN 19 (IO13)
 - ✓ PIN 20 (IO14)
- ▼ Analog Comparators
 - ✓ A CMP0H
 - ✓ A CMP0H
 - ✓ A CMP2L
 - ✓ A CMP3L
- ▼ Combination Function Components
 - ✓ FILTER_EDGE DET
 - ✓ 2-bit LUT0/DFF/LATCH0
 - ✓ 2-bit LUT1/DFF/LATCH1
 - ✓ 2-bit LUT2/DFF/LATCH2
 - ✓ 2-bit LUT3/PGEN
 - ✓ 3-bit LUT0/DFF/LATCH3
 - ✓ 3-bit LUT1/DFF/LATCH4
 - ✓ 3-bit LUT2/DFF/LATCH5
 - ✓ 3-bit LUT3/DFF/LATCH6
 - ✓ 3-bit LUT4/DFF/LATCH7
 - ✓ 3-bit LUT5/DFF/LATCH8
 - ✓ 3-bit LUT6/Pipe Delay/Ripple Counter
- ▼ Multi-functional Components
 - ✓ MF0 (4-bit LUT0, DFF/LATCH9, WS Cnt, 16-bit CNT0/DLY0/FS...
 - ✓ MF1 (3-bit LUT7, DFF/LATCH10, 8-bit CNT1/DLY1)
 - ✓ MF2 (3-bit LUT8, DFF/LATCH11, 8-bit CNT2/DLY2)
 - ✓ MF3 (3-bit LUT9, DFF/LATCH12, 8-bit CNT3/DLY3)
 - ✓ MF4 (3-bit LUT10, DFF/LATCH13, 8-bit CNT4/DLY4)
 - ✓ MF5 (3-bit LUT11, DFF/LATCH14, 8-bit CNT5/DLY5)
 - ✓ MF6 (3-bit LUT12, DFF/LATCH15, 8-bit CNT6/DLY6)
 - ✓ MF7 (3-bit LUT13, DFF/LATCH16, 8-bit CNT7/DLY7)
- ▼ Special Components
 - ✓ P DLY
 - ✓ VREF0
 - ✓ VREF1
 - ✓ POR
 - ✓ OSC0
 - ✓ OSC1
 - ✓ OSC2
 - ✓ I2C
 - ✓ TEMP SENSOR
 - ✓ BG
 - ✓ EEPROM



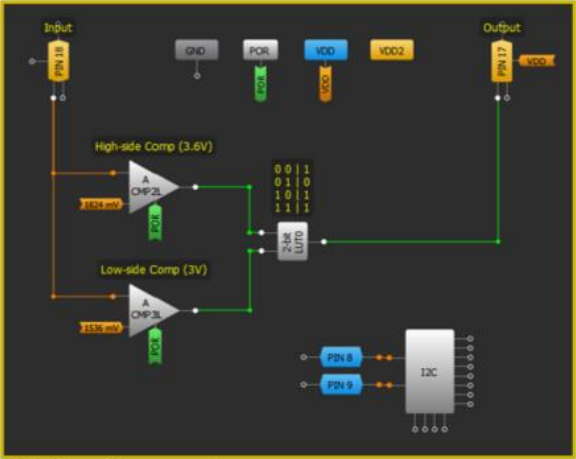
Create unique solution



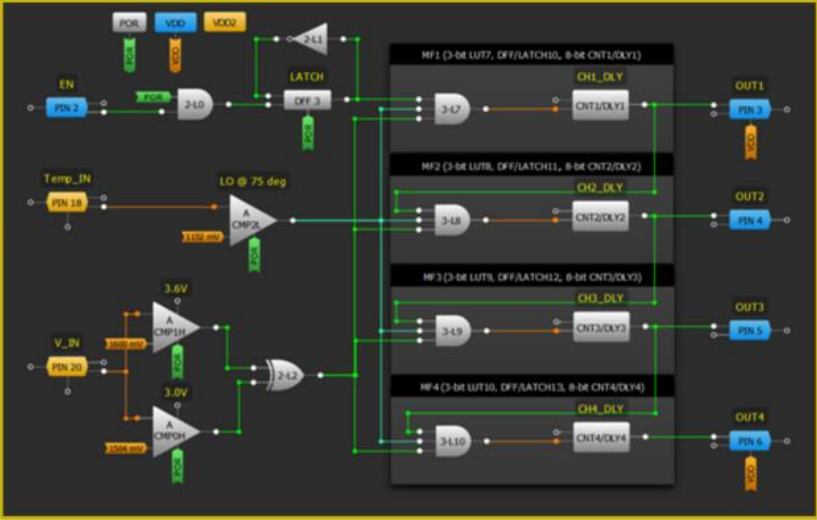
Power Sequencing



Overtemperature Detection



Window Comparator



Unique Solution



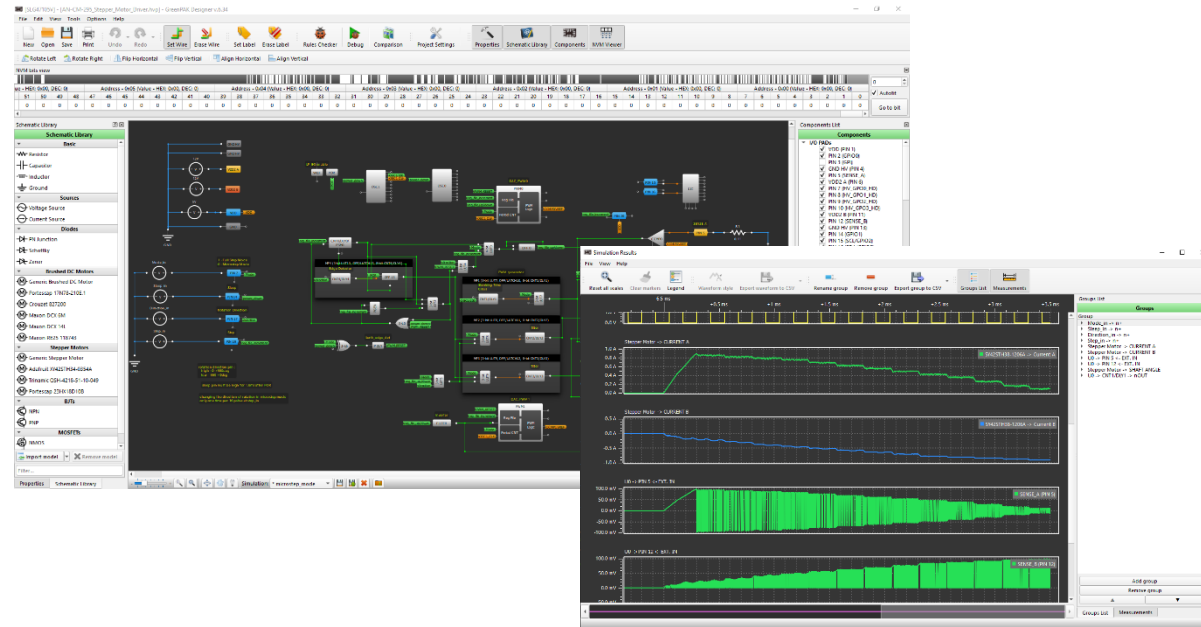
Minimize Components, Reduce PCB Space, and Lower Power

GreenPAK is ideal for

- Functional replacement of popular mixed-signal standard products and stand-alone discrete circuits
- Providing reliable hardware supervisory functions for devices such as SoCs and Microcontrollers

Easy & fast development tools

- GUI-based GreenPAK Designer software
- Development Kits for circuit emulation and IC programming



1.0 mm x 1.2 mm
0.4 mm pitch
STQFN
8-pin package



1.6 mm x 1.6 mm
0.4 mm pitch
STQFN
12-pin package



1.6 mm x 2.0 mm
0.4 mm pitch
STQFN
14-pin package



2.0 mm x 2.2 mm
0.4 mm pitch
STQFN
14-pin package



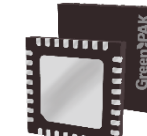
1.6 mm x 2.5 mm
0.4 mm pitch
STQFN
14-pin package



2.0 mm x 3.0 mm
0.4 mm pitch
STQFN
20-pin package



2.0 mm x 2.2 mm
0.4 mm pitch
MSTQFN
22-pin package



4.0 mm x 4.0 mm
0.4 mm pitch
STQFN
32-pin package

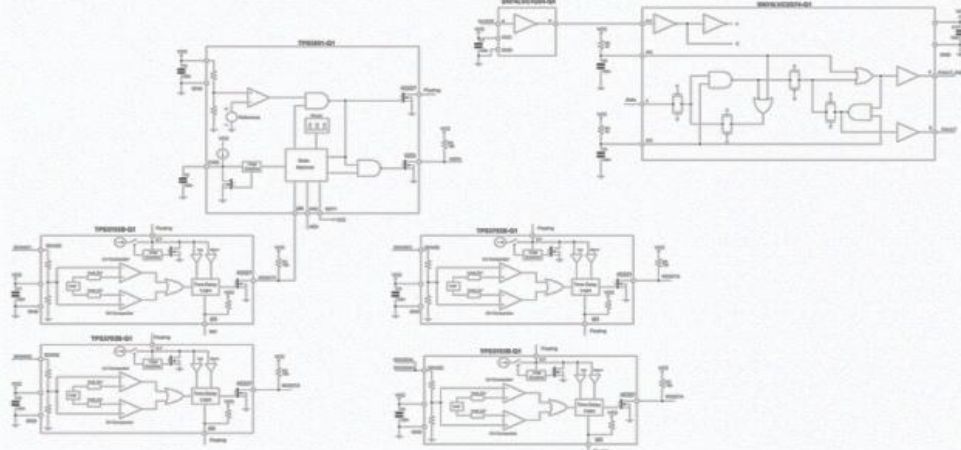


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GreenPAK Approach – from Concept to application

GreenPAK Implementation

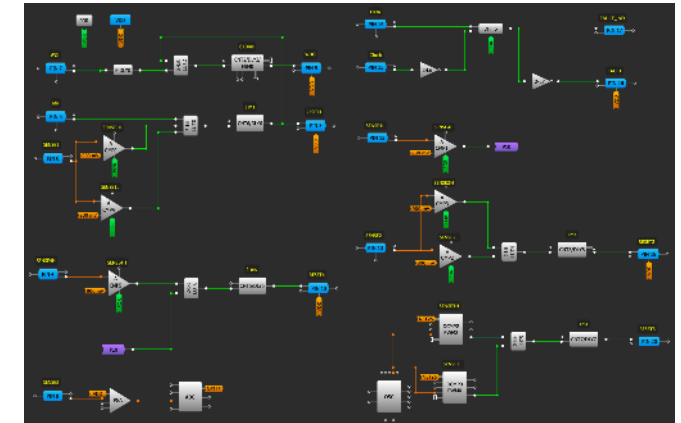
Implementation with Discrete Components



4 Rail Window Comparator+WD+ Reset Circuit

Components	Volume Price	Component Size (mm ²)	Component + Clearance
4 Rail Supervisors IC	\$ 1.04	9	11.25
1 Watchdog	\$ 0.27	9	11.25
1 D FF w/Clear & Preset	\$ 0.11	6.72	8.4
15 Passives	~ 0	~2.4*15 = 36	36
Inverter	\$ 0.04	9	11.25
Total	\$ 1.46	69.72 mm²	*78.15 mm²

*Assumed clearance = 25% of component size and 0 clearance for passives



- ✓ Replace all discrete components
 - Save pick & place costs
 - Reduce reliability & sourcing issues
- ✓ 3x lower price
- ✓ 6 times smaller solution
- ✓ Secure design
- ✓ Enable easy, low cost changes throughout development



Size – **13 mm² TQFN**
 Volume price: **< \$ 0.40**

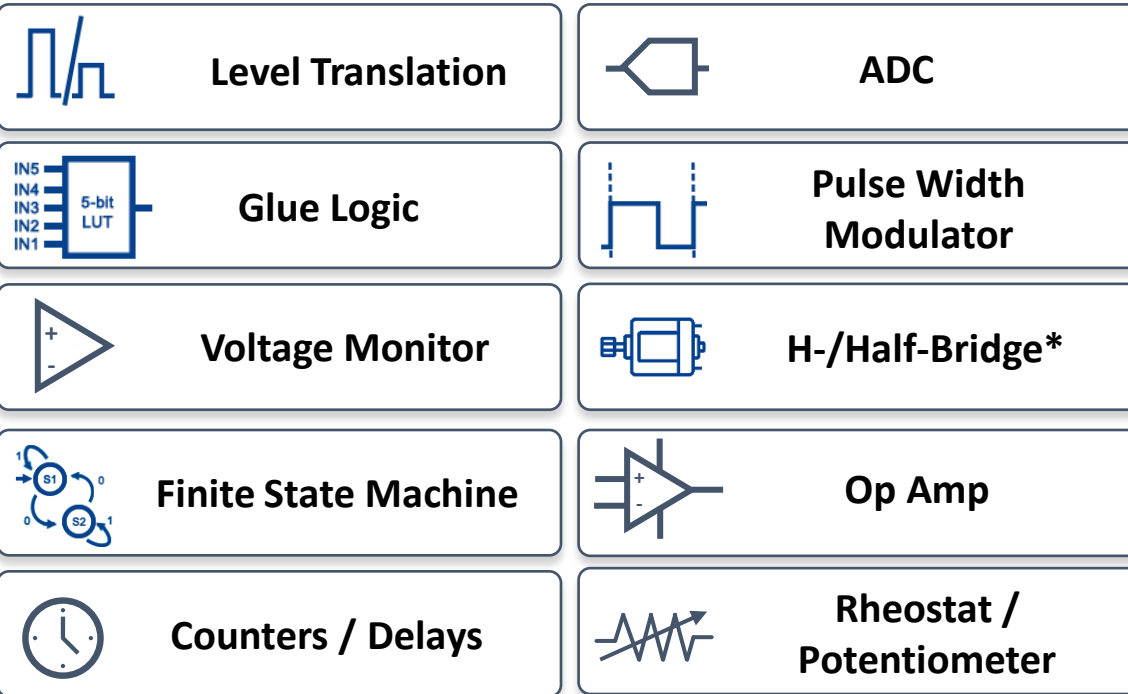
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What can I do with GreenPAK™?

GreenPAK Functions



Example Applications

- Supervisory Circuits
- System Reset
- LED Control
- Motor & Fan Control
- Power Sequencing
- Voltage Detection
- Frequency Detection
- Sensor Interface
- Port Detection
- Temperature Control
- Battery Monitor
- See [COOKBOOK](#) for more!

★ Multiple functions & applications can be combined into one IC

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GreenPAK is Cost effective

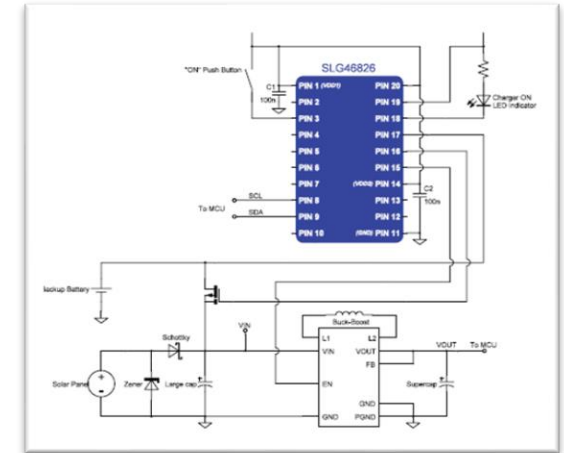
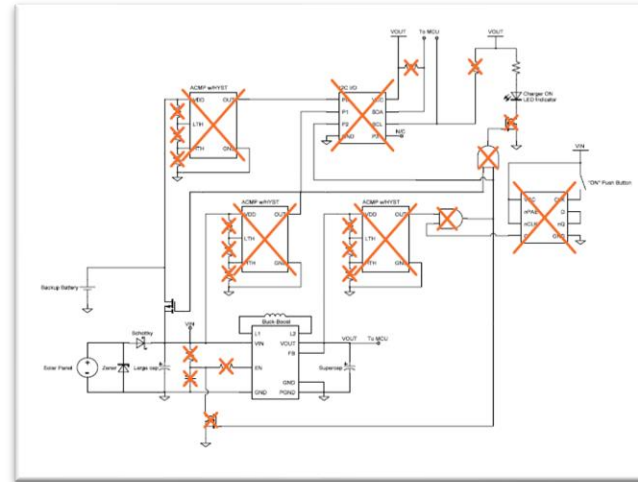
Integrating multiple discrete ICs & passives into GreenPAK lowers design cost

GreenPAK IC Costs

- Entire portfolio designed to be cost effective
- Fit as much as you can into GreenPAK*
- Average pricing between **~\$0.10 - \$0.50****
- Auto GreenPAK between **~\$0.35 - \$0.70****

Other Costs Benefits

- *No coding required* – streamlined design time
- Reduced prototyping time
- Reduces need for additional components
- Design changes are quick and inexpensive



Simple or Small Design



More Complex Designs / Higher Integration

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* Cost independent of circuit design
** Volume dependent

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What Are the GreenPAK Benefits?



Integrate and Differentiate

Implement new features and functionality in one device as small as 1.0 mm x 1.2 mm



Shrink PCB Footprint

Fewer components and less routing complexity



Reduce Power Consumption

Extend battery life by powering fewer discrete devices and dynamically managing power within the GreenPAK



Adapt Design as Needed

Adapt to changing requirements quickly and spin new prototypes in minutes



Faster Time to Market

Development tools exploit the power of silicon without NRE charges and long lead times



Secure

Circuit implementation is not visible to competition

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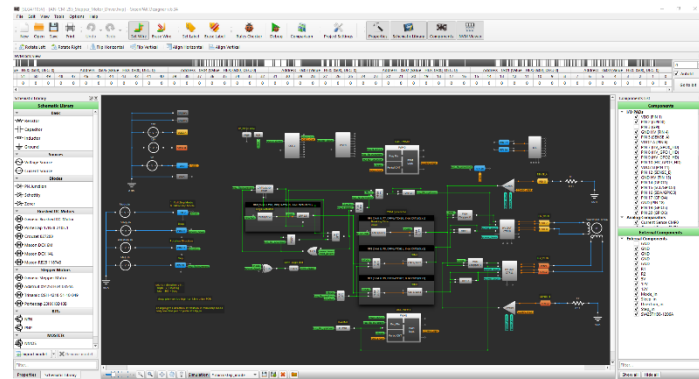
GreenPAK Design Development process

- Development with GreenPAK is **FAST**
- Create a custom design and debug with Evaluation Kit, or program individual ICs at your fingertips



Design Revisions?

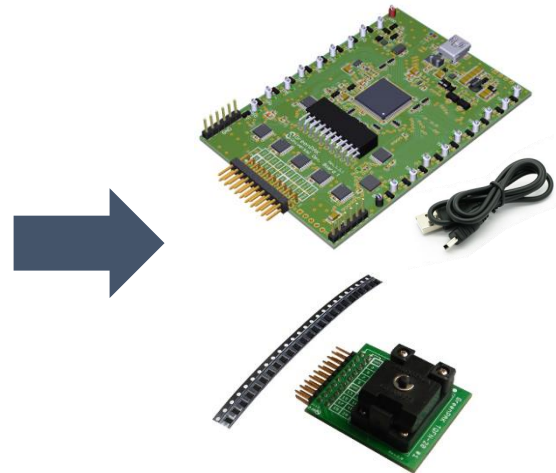
Ready for Production Samples?



GreenPAK Design Created

Design in as little as a few minutes with the [FREE Go Configure Software Hub](#).

Circuit design is done via SW
No EVK needed for creation of design!



Can Use EVK to Test & Debug*

Custom design can be tested with EVK or **FREE** samples requested from Renesas



Program at Your Desk

Can program prototype ICs at your fingertips or ask Renesas for **FREE** programmed samples

Production Samples Process Covered on Next Slide



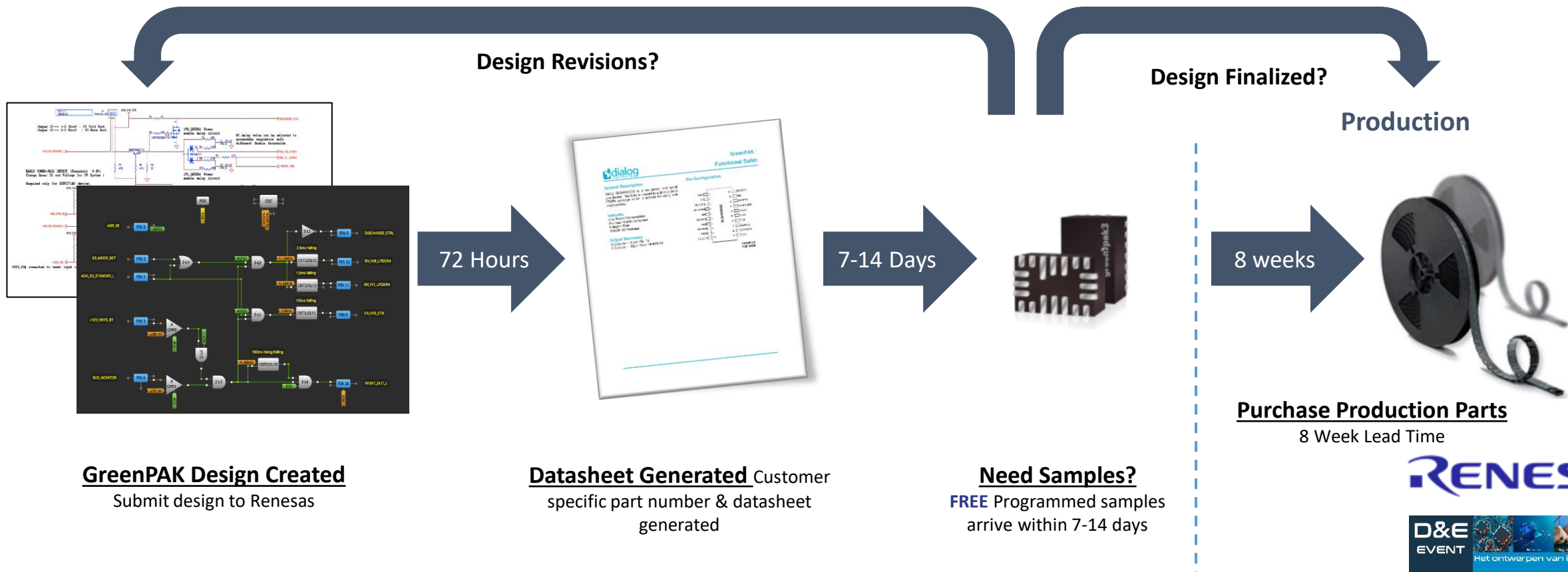
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GreenPAK Sample & Production Flow

- Design changes can be made throughout the development cycle
- Datasheet revision and part top markings reflect different versions of the device through development



Selecting Right GreenPAK For Design

Best GreenPAK for application dependent on design requirements

Picking Right Base Die

- Number of GPIO? (6 to 28)
- What is VDD? (1.0V to 5.5V)
- Need for VDD2? (Yes or No)
- SPI or I2C? (Yes, or not required)
- MTP (Multiple-Time Programmable) or OTP?
- Number of voltage rails being monitored?

What Functions / Features?

- With many use cases for GreenPAK it is important to determine which functions and features would be utilized. Examples Include:

Analog	Digital
<ul style="list-style-type: none"> ■ Analog switch ■ Battery charge indicator ■ Comparators ■ Current sense/limiter ■ LDOs ■ Low voltage indicator ■ Logic (Mux, gates, etc.) 	<ul style="list-style-type: none"> ■ OpAmp ■ Over-temp detection ■ Potentiometer ■ Rheostat ■ Voltage level detection ■ Wake/sleep function ■ and More
	<ul style="list-style-type: none"> ■ Control ■ Deserialization/serialization ■ Frequency detector ■ Frequency divider ■ GPIOs (6-28) ■ H-/Half-Bridge ■ I²C expansion ■ Interrupt ■ LED driving/pattern
	<ul style="list-style-type: none"> ■ Level shifting ■ Motor driving ■ Pattern generator ■ PWM generation ■ Sequencer ■ SPI or I²C Communication ■ System reset ■ Watchdog timer ■ and More

Selecting GreenPAK

- Filter by parametric search on web
- Reach out to Renesas FAE for support
- Email GreenPAK team for help to ID GreenPAK part for design
- Email both for design support
- GreenPAKsupport@Renesas.com

Simple or Small Design

More Complex Designs / Higher Integration



1.0 mm x 1.2 mm
0.4 mm pitch
STQFN
8-pin package



1.6 mm x 1.6 mm
0.4 mm pitch
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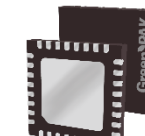
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GreenPAK Development Tools Overview

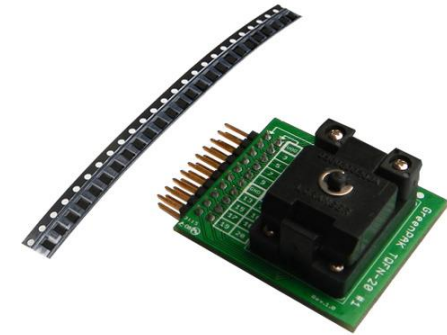
- **SLG4DVKADV** – GreenPAK Advanced Development Board

- EVK to program individual ICs & test GreenPAK designs
- Do not need EVK to do GreenPAK design
- [SLG4DVKADV - GreenPAK Advanced Development Board | Renesas](#)



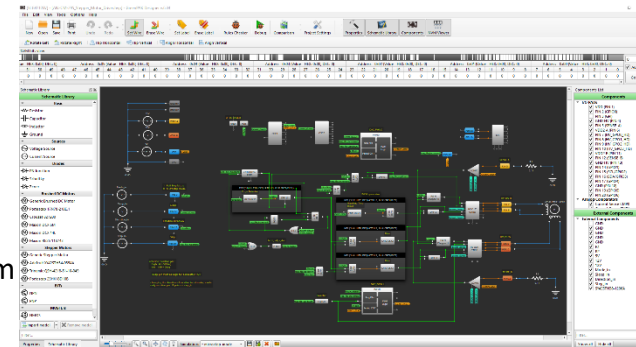
- **Socket Adapters**

- Each GreenPAK IC has a corresponding socket adapter for use with dev board
- SLG46018V-SKT shown here on slide for reference
- [SLG46108V-SKT - GreenPAK SLG46108 Development Kit with Socket Adapter | Renesas](#)



- **Go Configure Software Hub** – Design Software for GreenPAK

- Used for GreenPAK circuit design (**FREE DOWNLOAD**)
- Supports GreenPAK & ForgeFPGA design through GUI design environment
- No code required, Faster configuration, programming, and testing of custom
- [Go Configure Software Hub - GreenPAK Designer | Renesas](#)



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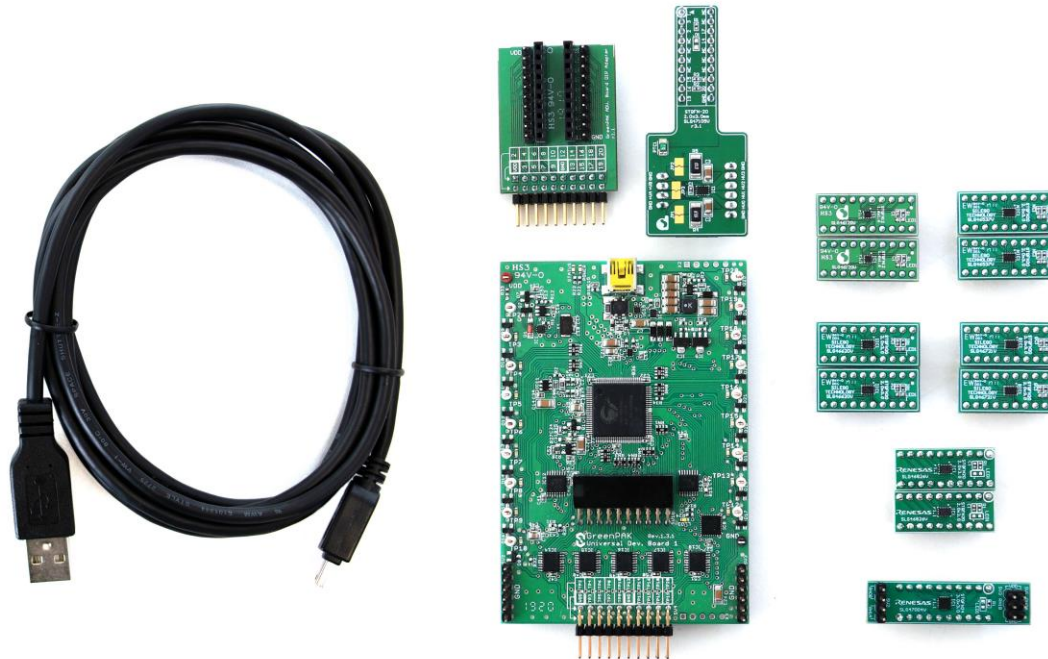
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GreenPAK Development Tools – starting with hardware

Where to start with hardware:

- If hardware is required Renesas FAE or GreenPAK product line can provide feedback on which tools / devices to begin design with
- Another option is the [SLG4DVKINTRO – GreenPAK Introduction Kit](#) which includes:

- 1x Universal Development Board (this might later change to the Lite board, but for now it is Advanced Dev Board)
- 1x USB cable
- 1x SLG4SADIP
- 2x SLG46120V-DIP
- 2x SLG46721V-DIP
- 2x SLG46620V-DIP
- 2x SLG46537V-DIP
- 2x SLG46826V-DIP
- 1x SLG47105V-DIP
- 1x SLG47004V-DIP



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GreenPAK Design Steps Are Fast



Design in minutes
Prototype in hours



No NRE



No Production
Commitment



8 Week
Production
Lead-time



Custom
Datasheet



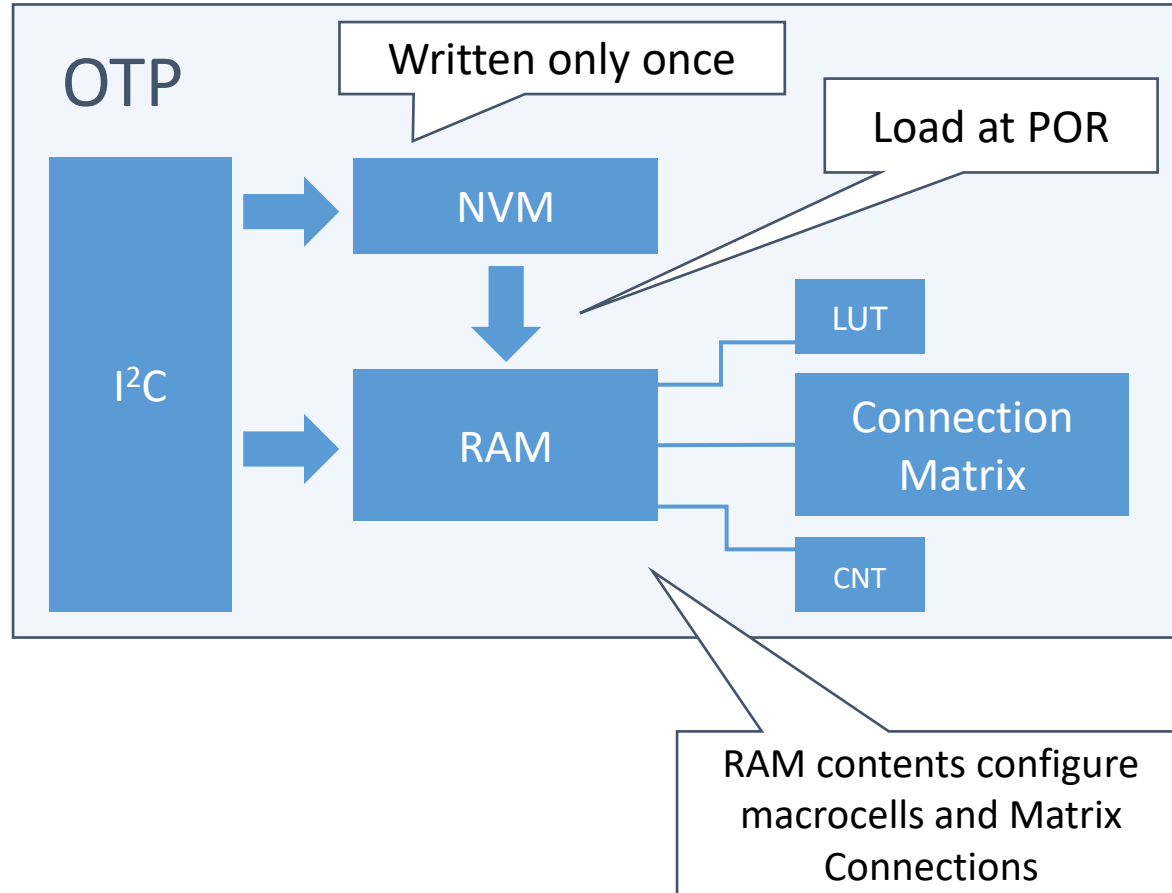
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Structure of the GreenPAK IC Memory - OTP

How IC Memory Works in OTP and MTP/ISP Circuits



- During start NVM memory is emulated to RAM.
- Inside the NVM, there is a specifically dedicated protection page, MTP enables to change security settings.

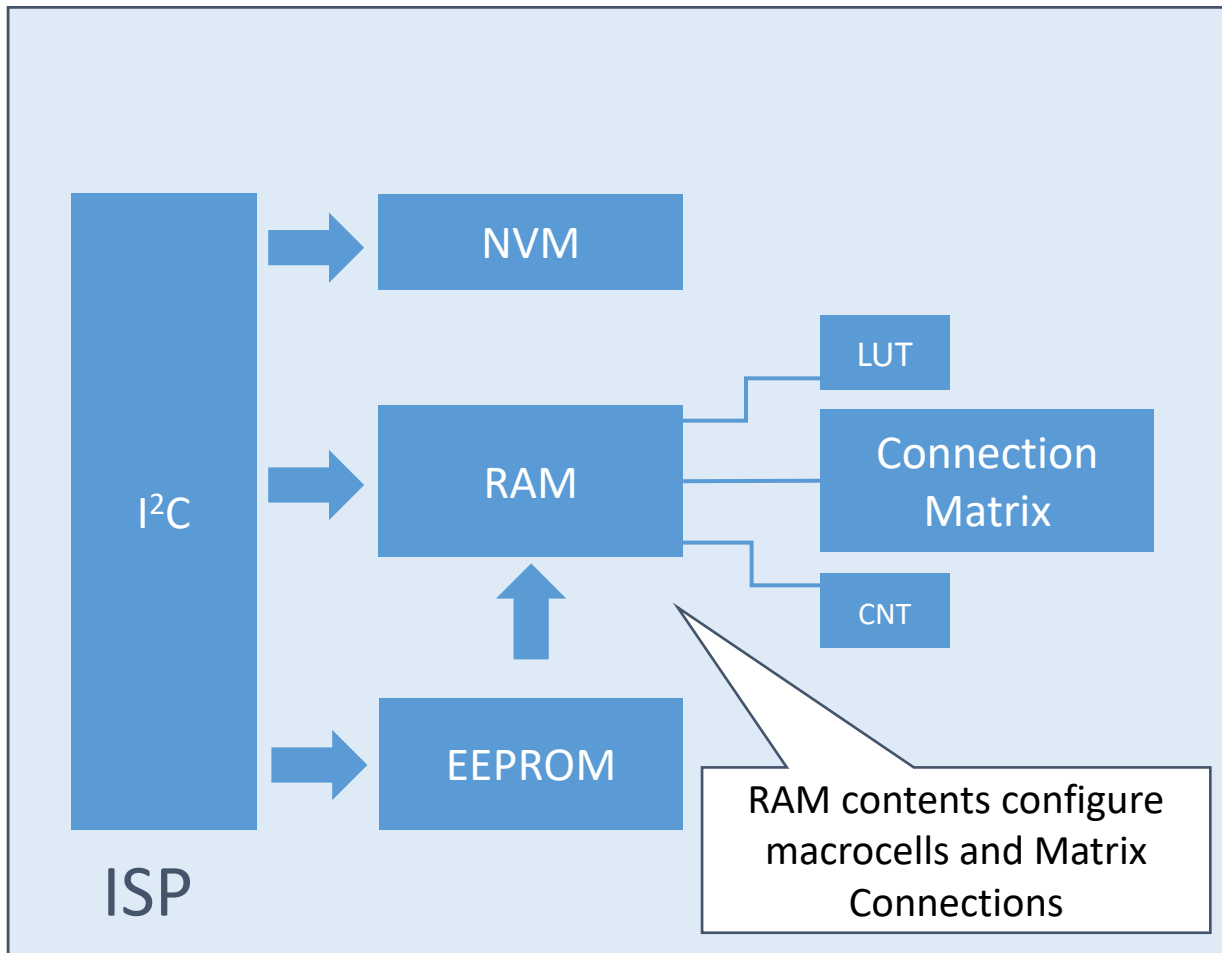
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Structure of the G_{reen}PAK IC Memory - ISP

How IC Memory Works in OTP and MTP/ISP Circuits



- During start NVM memory is emulated to RAM.
- Inside the NVM, there is a specifically dedicated protection page, MTP enables to change security settings.
- ISP device can write to EEPROM via I²C and from EEPROM to RAM.

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A Wide Family of Products for Many Applications

Overview of Existing Subfamilies

GreenPAK	HVPAK	Automotive GreenPAK
<ul style="list-style-type: none">▪ Dual Supply GreenPAK▪ GreenPAK with Load Switches▪ GreenPAK with Asynchronous State Machine▪ GreenPAK with Low Drop Out Regulators▪ GreenPAK with In-System Programmability▪ PN*: SLG46xxx and SLG47xxx <p>More Info</p>	<ul style="list-style-type: none">▪ Programmable Mixed-Signal ASIC with High Voltage Features▪ Integrated High Voltage up to 26.4 V and High Current up to 3 A Output Drivers*▪ PN: SLG471xx <p>More Info</p>	<ul style="list-style-type: none">▪ Cost-effective NVM programmable devices allowing to integrate many system functions into a single AEC-Q100 qualified IC▪ PN: SLG46xxx-A <p>More Info</p>
	AnalogPAK	Power GreenPAK
	<ul style="list-style-type: none">▪ Programmable Mixed-Signal ASIC with Analog Features▪ Rich set of analog blocks (OpAmp's, digital rheostats, etc.)▪ MTP NVM with in-system programmability▪ PN: SLG470xx <p>More Info</p>	<ul style="list-style-type: none">▪ High PSRR, low noise multi-output LDO IC for advanced camera and sensor systems▪ PN: SLG5100x <p>More Info</p>

* PN stands for part number

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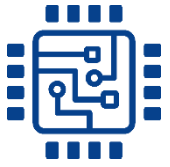
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[Go Configure™ Software](#)

Schematic capture-like tool allowing design, configuration, and programming



[GreenPAK Cookbook](#)

Outlines different techniques and provides completed applications for reference



[Application Notes](#)

Collection of application specific collateral documenting design process for various solutions using GreenPAK



[GreenPAK Forum](#)

Online community for questions and support on everything GreenPAK



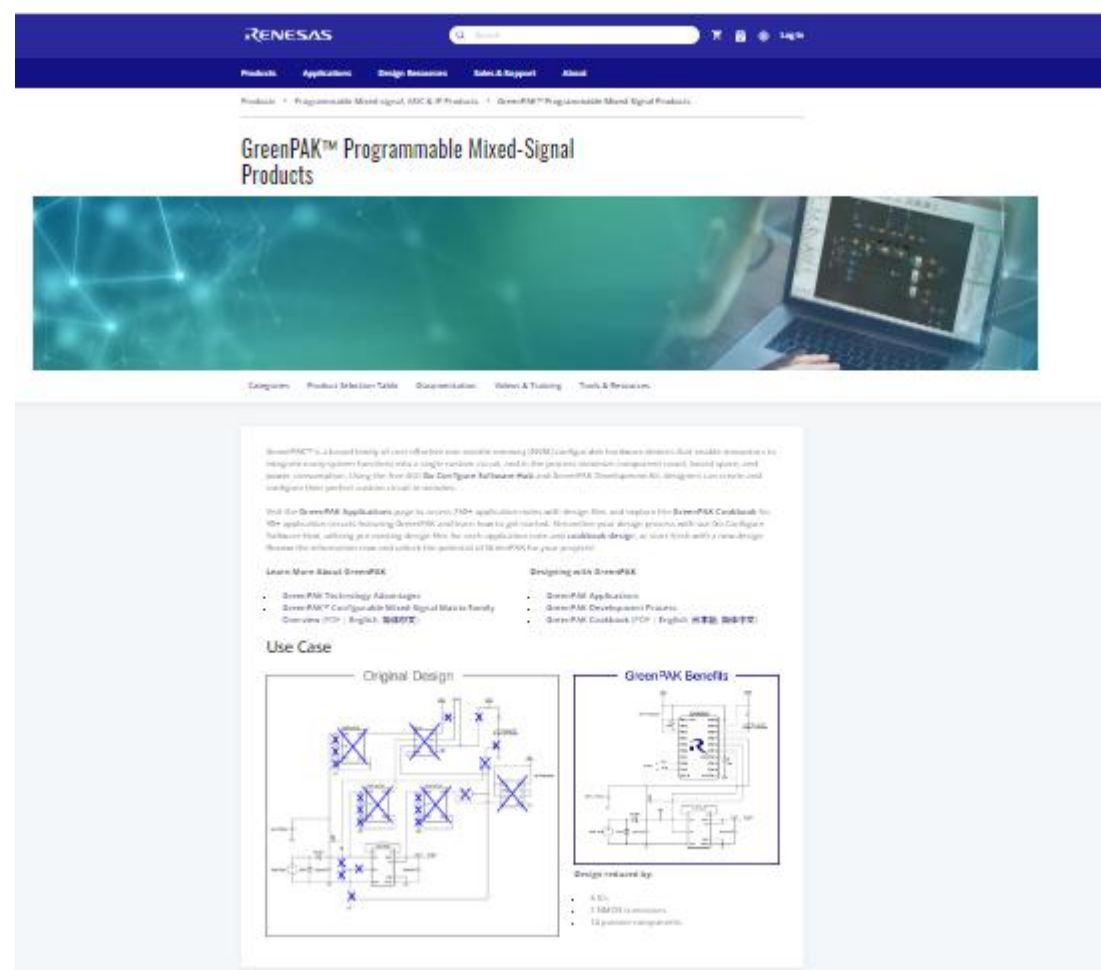
[GreenPAK Partners](#)

Certified experienced GreenPAK third-party design partners



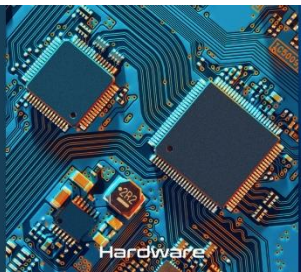
[FAQs](#)

Knowledge base addressing common questions



[GreenPAK™ Programmable Mixed-Signal Products | Renesas](#)

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